



# IEEE/SICE SII 2024

International Symposium on System Integration  
HA LONG, VIETNAM 8-11<sup>th</sup> January, 2024



IEEE



Ha Long Bay

IEEE/SICE International Symposium on System Integration (SII) is the symposium series presenting the state of the art and future perspectives of system integration, where industrial experts, researchers, and academics share ideas and experiences surrounding frontier technologies, breakthrough and innovative solutions, and applications.

The IEEE/SICE SII 2024 will be the 16th symposium on system integration. System integration is one of the key technologies and the integration of hardware and software is especially important to solve the industrial or social system problems in the new century. This symposium focuses towards new research and industrial applications of system integration, and discusses approaches and methodologies to improve effectiveness of system integration.

## Important Dates:

Proposals for Special Sessions

Jun. 30, 2023

**Paper Submission**

**Aug. 1, 2023**

Workshop Proposal Submission Deadline

Aug. 15, 2023

Notification of Workshop Proposal Acceptance

Sep. 15, 2023

Notification of Paper Acceptance

Oct. 1, 2023

Final Paper Submission

Oct. 15, 2023

Late Breaking Results Submission

Oct. 15, 2023

Notification of Late Breaking Results Acceptance

Oct. 29, 2023



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※ All proceedings will be published on IEEE Xplore, and indexed by Web of Science and Scopus.

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